

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of the claims in the application:

Listing of Claims:

1. – 16. (Canceled)

17. (Currently Amended) A method of processing a wafer comprising:  
placing a wafer atop a wafer chuck, the chuck having a base and an upper body in which the upper body is coupled to the base by a flexible coupling that allows the upper body to tilt relative to the base;

engaging the wafer to a hollow sleeve which forms an enclosing vessel to retain a processing fluid therein, the wafer forming a floor of the vessel; and

preventing or reducing leakage of the processing fluid by tilting of the wafer to allow for a compliant engagement of the wafer and the sleeve.

processing the wafer utilizing the processing fluid, wherein tilting of the wafer allows for a compliant engagement of the wafer and the sleeve to prevent or reduce leakage of the processing fluid.

18 (Original) The method of claim 17 further comprising the raising of at least one lift pin through the upper body to raise the wafer off of the upper body for removal of the wafer from the wafer chuck.

19. (Previously Presented) The method of claim 17 wherein processing the wafer includes using the processing fluid to deposit copper material onto the wafer.

20. (Previously Presented) The method of claim 17 wherein processing the wafer includes using the processing fluid to remove copper materials from the wafer.